PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7191075

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WAI MUN LEE	02/14/2022
HUI BOON CHUA	02/11/2022
ALEXANDER OON	02/14/2022
KEE SIN THONG	02/15/2022
SOON LENG YAP	02/14/2022

RECEIVING PARTY DATA

Name:	MOTOROLA SOLUTIONS, INC.
Street Address:	500 W. MONROE STREET
City:	CHICAGO
State/Country:	ILLINOIS
Postal Code:	60661

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17651302

CORRESPONDENCE DATA

Fax Number: (414)277-0656

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 414-271-6560
Email: mkeipdocket@michaelbest.com, MSIdocketing@motorolasolutions.com, ectressler@michaelbest.com
Correspondent Name: MICHAEL BEST & FRIEDRICH LLP (MOTOROLA S
Address Line 1: 790 N. WATER STREET
Address Line 2: SUITE 2500
Address Line 4: MILWAUKEE, WISCONSIN 53202

ATTORNEY DOCKET NUMBER:	PAT27460-US-PRI
NAME OF SUBMITTER:	/ELIZABETH TRESSLER/
SIGNATURE:	/elizabeth tressler/
DATE SIGNED:	02/23/2022

Total Attachments: 6

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **WAI MUN LEE,** residing in Ipoh, Perak, Malaysia, **HUI BOON CHUA,** residing in Batu Pahat, Johor, Malaysia, **ALEXANDER OON,** residing in Bayan Lepas, Penang, Malaysia, **KEE SIN THONG,** residing in Butterworth, Penang, Malaysia, and **SOON LENG YAP,** residing in Kuala Kangsar, Perak, Malaysia, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto MOTOROLA SOLUTIONS, INC., a corporation of the State of Delaware, having its principal office in Chicago, State of Illinois, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **DYNAMIC RFPA OPERATING MODES FOR A CONVERGED COMMUNICATION DEVICE** (Docket No. **PAT27460-US-PRI**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any non-provisional, division, extension, continuation, re-examination, or reissue thereof.

We hereby also sell, assign and transfer unto MOTOROLA SOLUTIONS, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize MOTOROLA SOLUTIONS, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to MOTOROLA SOLUTIONS, INC., for the sole use and benefit of MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to MOTOROLA SOLUTIONS, INC.

We agree that, when requested, we will, without charge to MOTOROLA SOLUTIONS, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives or nominees.

We covenant with MOTOROLA SOLUTIONS, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **Wai Mun Lee**

Signature: /WMLEE/ Date: 14 Feb 2022

(2) Legal Name of Inventor: **Hui Boon Chua**

Signature:____________________ Date:__________

(3) Legal Name of Inventor: **Alexander Oon**

Signature:____________________ Date:__________

(4) Legal Name of Inventor: **Kee Sin Thong**

Signature:____________________ Date:__________

(5) Legal Name of Inventor: **Soon Leng Yap**

Signature:____________________ Date:__________

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(1) Legal Name of Inventor: **Wai Mun Lee**

Signature:____________________ Date:__________

(2) Legal Name of Inventor: **Hui Boon Chua**

Signature: /CHUA HUI BOON/ Date: February 11, 2022

(3) Legal Name of Inventor: **Alexander Oon**

Signature:____________________ Date:__________

(4) Legal Name of Inventor: **Kee Sin Thong**

Signature:____________________ Date:__________

(5) Legal Name of Inventor: **Soon Leng Yap**

Signature:____________________ Date:__________

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Signature:____ Date:________________

(2) Legal Name of Inventor: **Hui Boon Chua**

Signature:____ Date:________________

(3) Legal Name of Inventor: **Alexander Oon**

Signature:____ Date: 14 Feb 2022

(4) Legal Name of Inventor: **Kee Sin Thong**

Signature:____ Date:________________

(5) Legal Name of Inventor: **Soon Leng Yap**

Signature:____ Date:________________

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Signature:____________________ Date:__________

(2) Legal Name of Inventor: **Hui Boon Chua**

Signature:____________________ Date:__________

(3) Legal Name of Inventor: **Alexander Oon**

Signature:____________________ Date:__________

(4) Legal Name of Inventor: **Kee Sin Thong**

Signature: /Kee Sin Thong/. Date: 15-Feb-2022

(5) Legal Name of Inventor: **Soon Leng Yap**

Signature:____________________ Date:__________

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Signature:____________________ Date:__________

(2) Legal Name of Inventor: **Hui Boon Chua**

Signature:____________________ Date:__________

(3) Legal Name of Inventor: **Alexander Oon**

Signature:____________________ Date:__________

(4) Legal Name of Inventor: **Kee Sin Thong**

Signature:____________________ Date:__________

(5) Legal Name of Inventor: **Soon Leng Yap**

Signature: /Soon Leng Yap/ Date: 14 February 2022